

EVS 3000

Intel® Core™ i9/i7/i5/i3 Processor (14th Gen)

Expandable AI Computing System with MXM Graphics

intel
partner
Gold
IoT Solutions

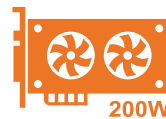


- High-performance platform: Intel® Core™ i9/i7/i5/i3 processors paired with Intel® R680E PCH, supporting CPUs up to 65W TDP
- Supports up to 115W NVIDIA® Quadro®/GeForce® MXM GPUs for advanced graphics performance
- 200W power capacity dedicated to multiple AI computing GPUs
- Equipped with 2 front-accessible M.2 slots and 2 2.5" SSD trays, plus a SIM socket for wireless connectivity
- USB 3.2 Gen 2x2 provides maximum data transfer rates of up to 20Gbps
- Wide-range DC power input from 9V to 55V, featuring Software Ignition Control for enhanced flexibility
- Allxon-powered out-of-band remote management for connected devices
- Fanless design supports operation in extreme temperatures from -25°C to 55°C

High-performance AI Inference Platform | Advanced Integration Industrial-grade Reliability | Diverse Configurations

The EVS-3000 Series is a fanless AI computing system built on the latest 14th Gen Intel Core i9/i7/i5/i3 processors. It features advanced I/O options, including USB Type-C, 2.5G LAN, and up to 4 PCIe slots for expansion. With support for up to 200W power for NVIDIA® or AMD graphics engines, the system delivers robust, high-performance computing, making it ideal for autonomous robotics, machine vision, public security, and other edge AI applications.

The series offers flexibility with 8 different models—EVS-3400(F), EVS-3300(F), EVS-3200(F), and EVS-3100(F)—providing scalable solutions for various project requirements. Additionally, Allxon-powered Out-of-Band management ensures efficient remote device control, enhancing productivity and remote management capabilities.



Specifications

RS-10012024

System

Processor	- 24-core Intel® Core™ i9/i7/i5/i3 Processor (14th gen, Raptor Lake-S Refresh) - 24-core 13th Gen Intel® Core™ i9/i7/i5/i3 Processor (Raptor Lake-S) - 16-core 12th Gen Intel® Core™ i9/i7/i5/i3 Processor (Alder Lake-S)
Chipset	Intel® R680E
BIOS	AMI
SIO	IT8786E
Memory	2 DDR5 SO-DIMM, up to 96GB (ECC/Non-ECC)
OS	Windows 11, Windows 10, Linux

I/O Interface

Serial	2 COM RS-232/422/485 (ESD 8kV)
USB	- 4 USB 3.2 Gen 2 Type A - 1 USB 3.2 Gen 2x2, USB Type-C supports max 20Gbps data transfer (15W, 5V/3A)
Isolated DIO	32 Isolated DIO : 16 DI, 16 DO
LED	Power, HDD, OOB
SIM Card	1 External SIM Card Socket for 5G/4G/LTE/GPRS/UMTS wireless network

Expansion

PCIe	Please refer to Order Information
M.2	- 1 M.2 Key B Socket (2280/3042/3052, PCIe/USB 3, default/SATA) - 1 M.2 Key E Socket (2230, PCIe/USB)

Graphics

Graphics Processor	Intel® UHD Graphics 770/730 driven by Intel® X® Architecture
Interface	Up to 7 independent displays : - 2 HDMI 2.1 : Up to 4096 x 2304 @60Hz - 1 DP : Up to 3840 x 2160 @60Hz - 4 DP : Up to 7680 x 4320 @60Hz (By requested MXM)

Storage

SATA	2 SATA III (6Gbps) support S/W RAID 0, 1 with 2 Front-access 2.5" SSD/HDD Tray
M.2	- 1 M.2 Key M Socket (2280, PCIe x4) - 2 Front-access M.2 Key M SSD Tray (EVS-3400/3300)

Audio

Audio Codec	Realtek® ALC888S-VD, 7.1 Channel HD Audio
Audio Interface	1 Mic-in, 1 Line-out

Ethernet

LAN 1	Intel® I226 2.5GigE LAN supports TSN
LAN 2	Intel® I226 2.5GigE LAN supports TSN

Power

Power Input	DC 9V to 55V
Power Interface	3-pin Terminal Block : V+, V-, Frame Ground
Ignition Control	16-mode Software Ignition Control
Remote Switch	3-pin Terminal Block

Out-of-Band Management

MCU	Nuvoton NUC980
Interface	OOB LAN, 10/100Mb Ethernet LAN, RJ45 Connector
Remote Management	Support Remote Power ON/OFF, Reset and Power Cycling

Others

TPM	Infineon SLB9670 supports TPM 2.0, SPI Interface
Watchdog Timer	Reset : 1 to 255 sec./min. per step
Smart Mgmt.	Wake on LAN, PXE supported
HW Monitor	Monitoring temperature, voltages. Auto throttling control when CPU overheats.

Mechanical

Dimensions	Please refer to Order Information
Weight	Please refer to Order Information
Mounting	- Wallmount by mounting bracket - VESA Mount (Optional) - DIN Rail Mount (Optional) - Rackmount (Optional)

Environment

Operating Temperature	- 35W TDP CPU : -25°C to 55°C (-13°F to 131°F) with air flow - 65W TDP CPU : -25°C to 45°C (-13°F to 113°F) with air flow
Storage Temperature	-40°C to 85°C (-40°F to 185°F)
Humidity	5% to 95% Humidity, non-condensing
Relative Humidity	95% @55°C
Shock	- IEC 60068-2-27 - SSD : 50G @wallmount, Half-sine, 11ms - MIL-STD-810G method 514.6, Category 4 (with PCIe Card)
Vibration	- IEC 60068-2-64 - SSD : 5Grms, 5Hz to 500Hz, 3 Axis - MIL-STD-810G method 516.6, Procedure I (with PCIe Card)
EMC	CE, FCC, ICES, EN50155, EN50121-3-2

Order Information

Model	Graphics MXM TDP	PCIe x8 Gen 4	PCIe x4 Gen 4	M.2 Tray	System Fan	Dimensions	Weight
EVS-3100	60W	1	-	-	-	280 mm x 90 mm x 215 mm (11.02" x 3.54" x 8.46")	5.0 kg (11.02 lb)
EVS-3200		1	1	-		280 mm x 114 mm x 215 mm (11.02" x 4.49" x 8.46")	5.6 kg (12.35 lb)
EVS-3300		1	2	2		280 mm x 130 mm x 215 mm (11.02" x 5.19" x 8.46")	6.2 kg (13.67 lb)
EVS-3400		1	3	2		280 mm x 152 mm x 215 mm (11.02" x 5.98" x 8.46")	6.8 kg (14.99 lb)
EVS-3100F	60W to 115W	1	-	-	Y	280 mm x 97 mm x 215 mm (11.02" x 3.82" x 8.46")	5.1 kg (11.24 lb)
EVS-3200F		1	1	-		280 mm x 121 mm x 215 mm (11.02" x 4.76" x 8.46")	5.7 kg (12.57 lb)
EVS-3300F		1	2	2		280 mm x 137 mm x 215 mm (11.02" x 5.39" x 8.46")	6.3 kg (13.89 lb)
EVS-3400F		1	3	2		280 mm x 159 mm x 215 mm (11.02" x 6.26" x 8.46")	6.9 kg (15.21 lb)